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(12) **United States Design Patent** (10) **Patent No.:** **US D896,183 S**
Musser et al. (45) **Date of Patent:** **** Sep. 15, 2020**

(54) **ELECTRICAL CABLE CONNECTOR**

(71) Applicant: **Samtec Inc.**, New Albany, IN (US)
(72) Inventors: **Randall Eugene Musser**, Enola, PA (US); **Jonathan Earl Buck**, Hershey, PA (US); **John Mongold**, Todd, PA (US)
(73) Assignee: **SAMTEC, INC.**, New Albany, IN (US)
(**) Term: **15 Years**
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(52) **U.S. Cl.**
USPC **D13/147**
(58) **Field of Classification Search**
USPC D13/146, 147, 123, 133, 137.1–139.8, D13/154
CPC H01R 9/223; H01R 9/2491; H01R 12/721; H01R 13/6585
See application file for complete search history.

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Primary Examiner — Bridget L Eland

(74) *Attorney, Agent, or Firm* — BakerHostetler

(57) **CLAIM**

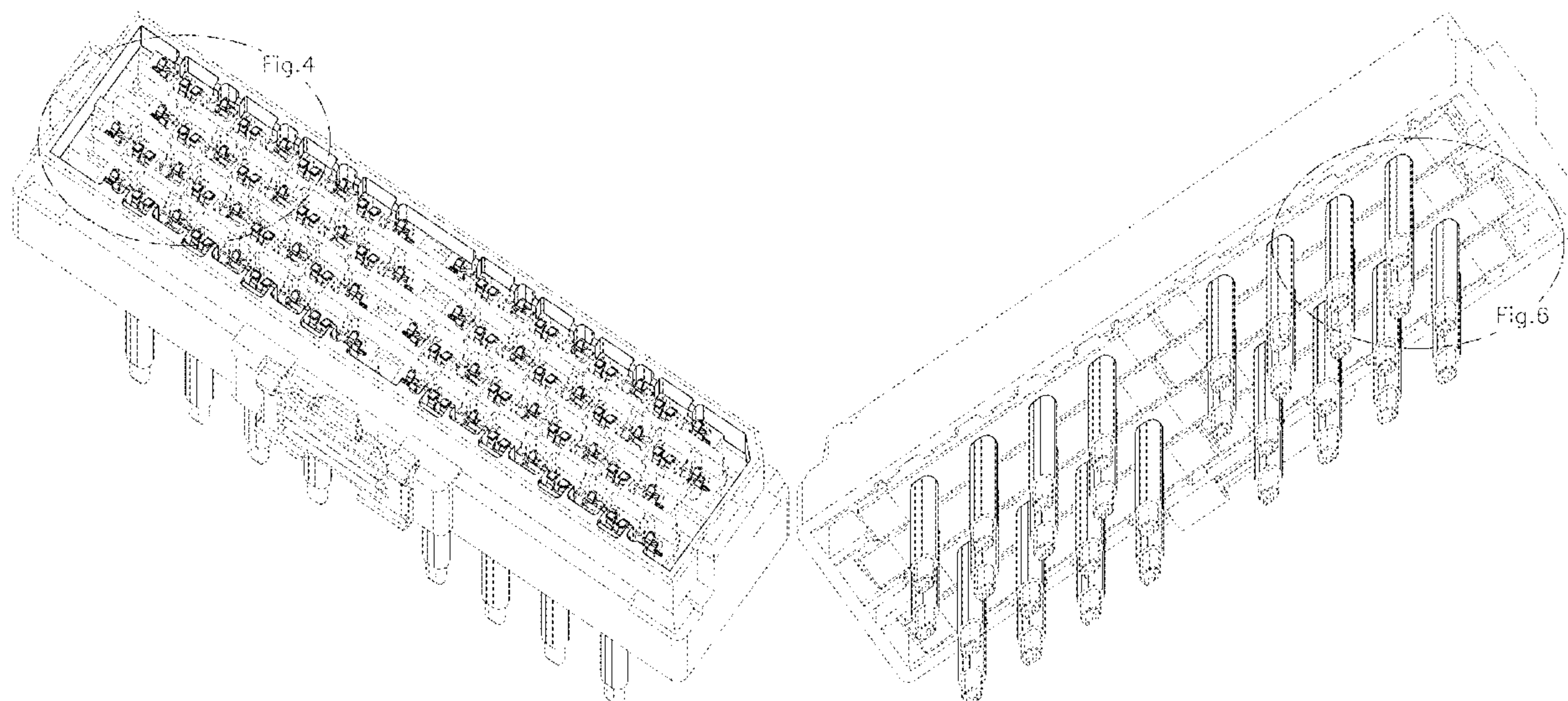
The ornamental design for an electrical cable connector, as shown and described.

DESCRIPTION

FIG. 1 is a top, front, right perspective view of an electrical cable connector according to our new design;
FIG. 2 is a bottom, rear, left perspective view thereof;
FIG. 3 is another front, top, right perspective view thereof;
FIG. 4 is an enlarged front, top, right perspective view of a portion thereof, as indicated at region FIG. 4 of FIG. 3;
FIG. 5 is another bottom, rear, left perspective view thereof;
FIG. 6 is an enlarged bottom, rear, left perspective view of a portion thereof, as indicated at region FIG. 6 of FIG. 5;
FIG. 7 is a top elevation view thereof;
FIG. 8 is a bottom elevation view thereof;
FIG. 9 is a left side elevation view thereof;
FIG. 10 is a right side elevation view thereof;
FIG. 11 is a front plan view thereof; and,
FIG. 12 is a rear plan view thereof.

The broken line portion of the figure drawings is included to show unclaimed subject matter only for the purpose of illustrating environment and forms no part of the claimed design. In addition, the surfaces in the views between the claimed solid line edges and the broken lines form no part of the claimed design.

1 Claim, 5 Drawing Sheets



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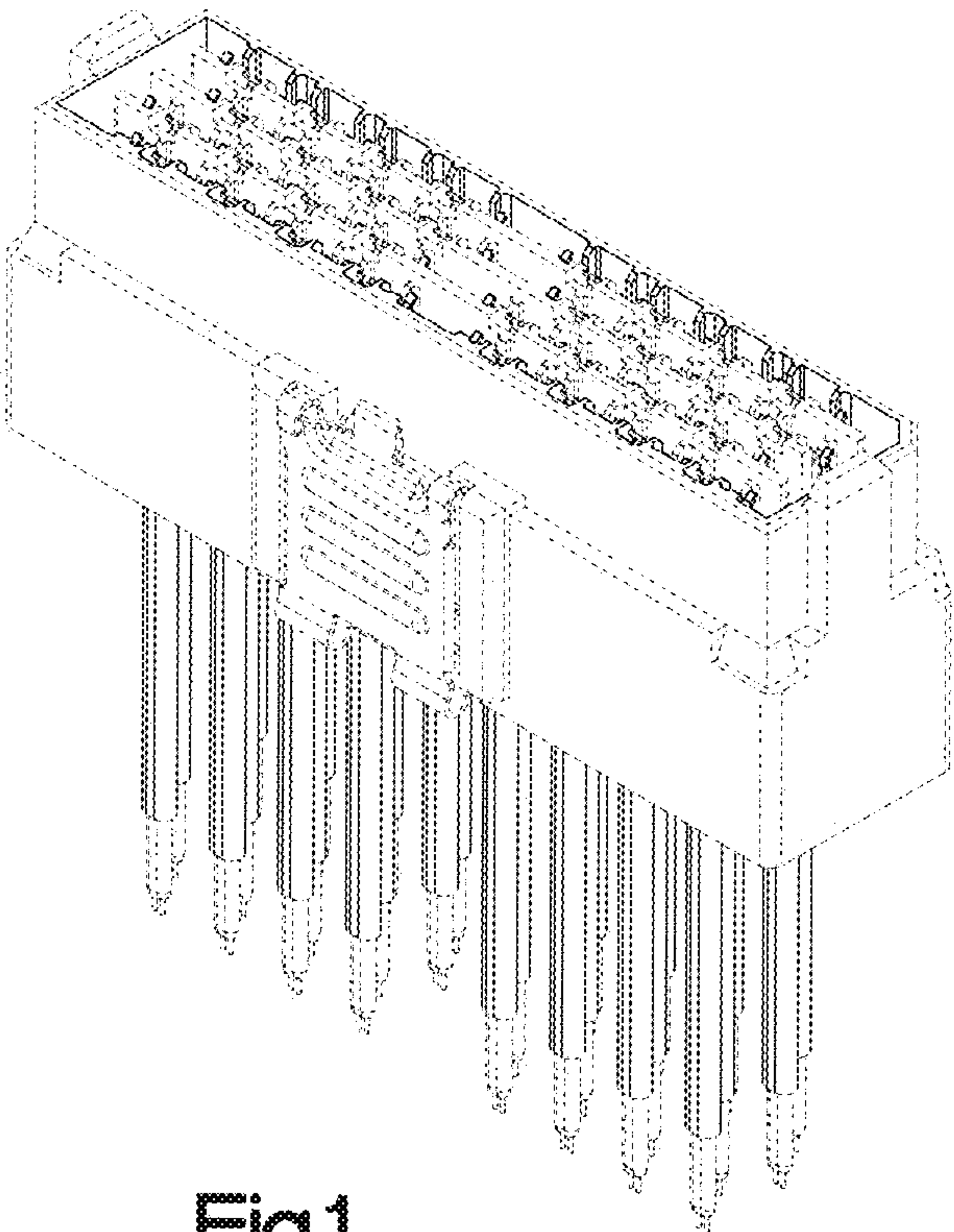


Fig.1

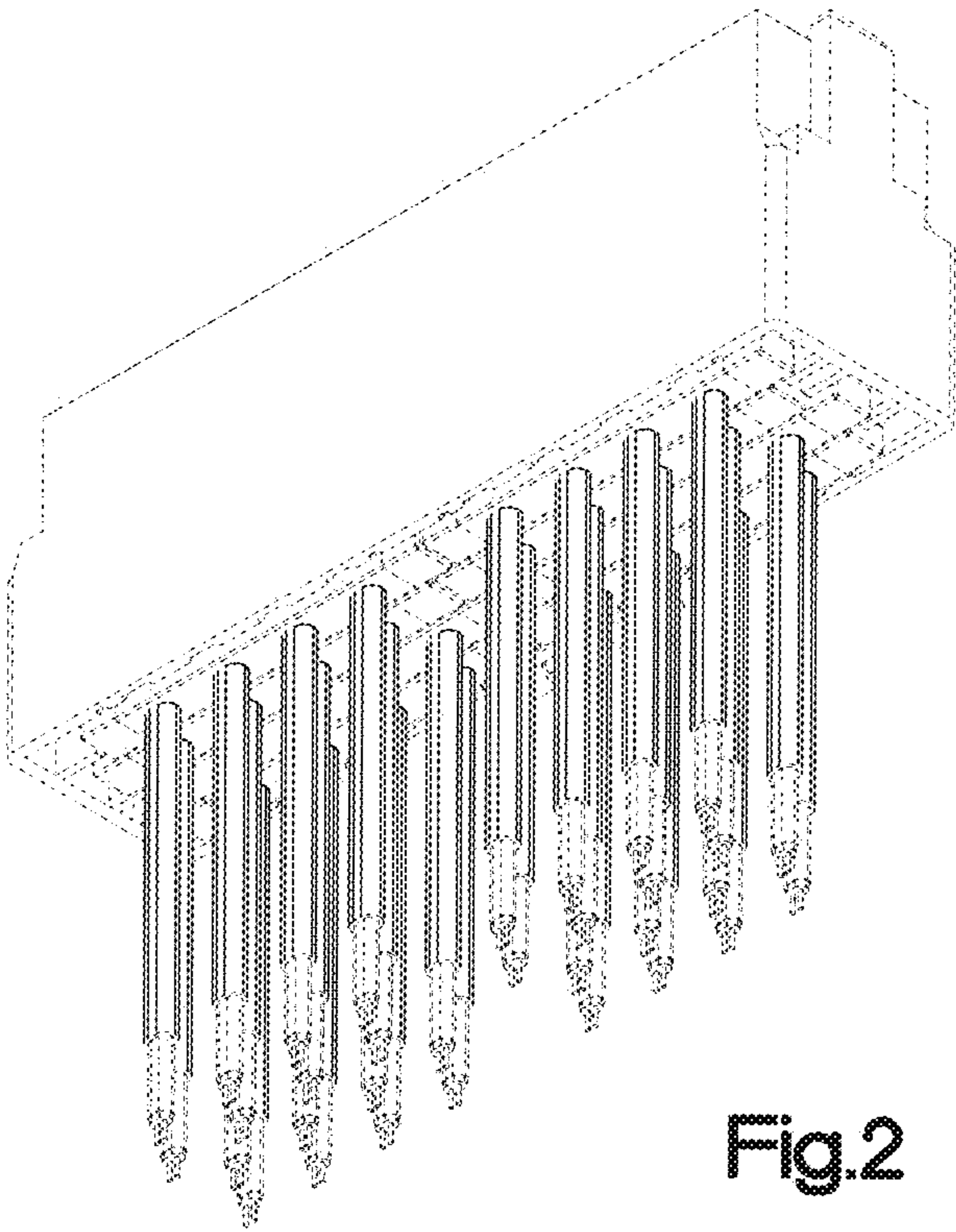


Fig.2

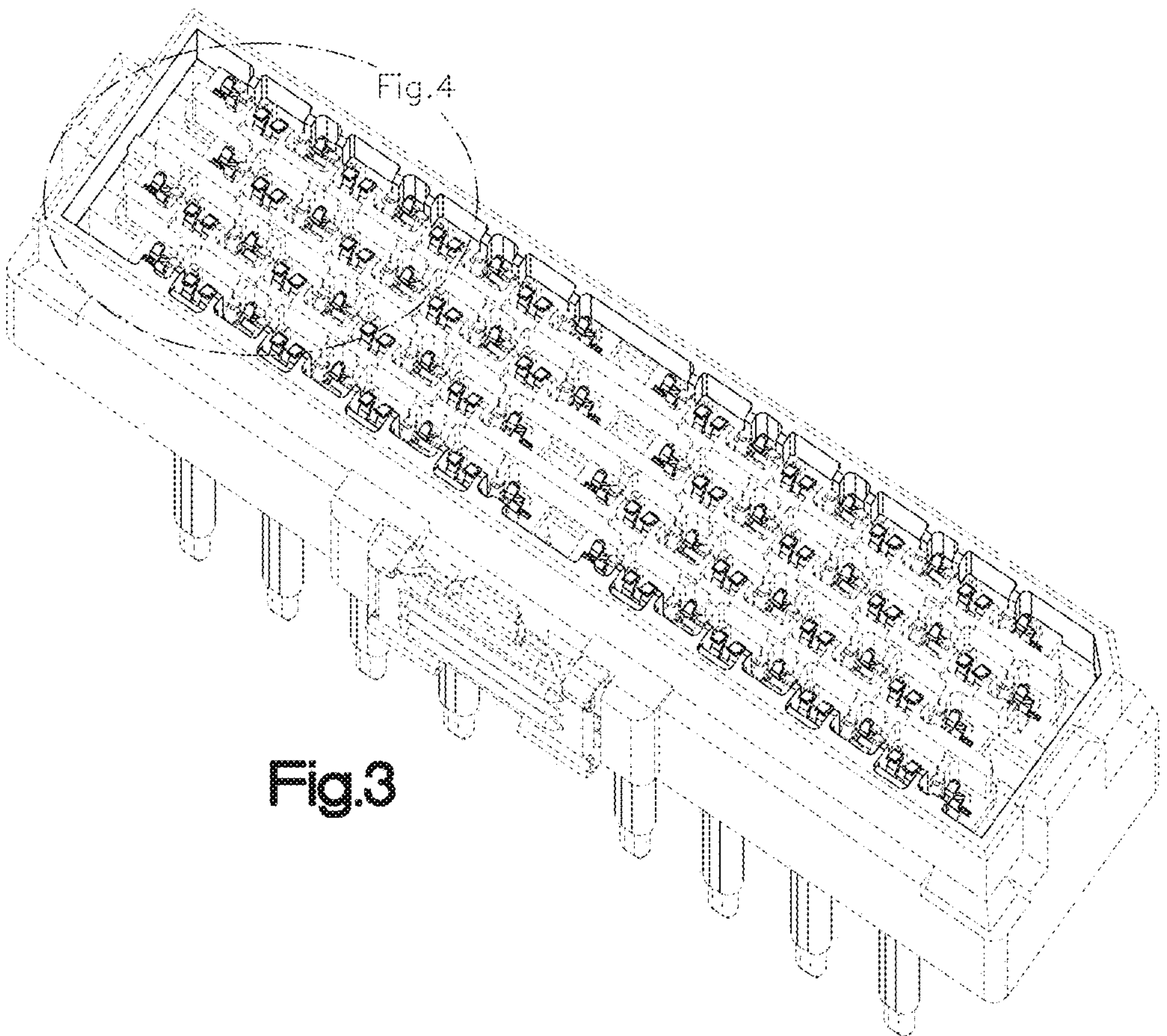


Fig.3

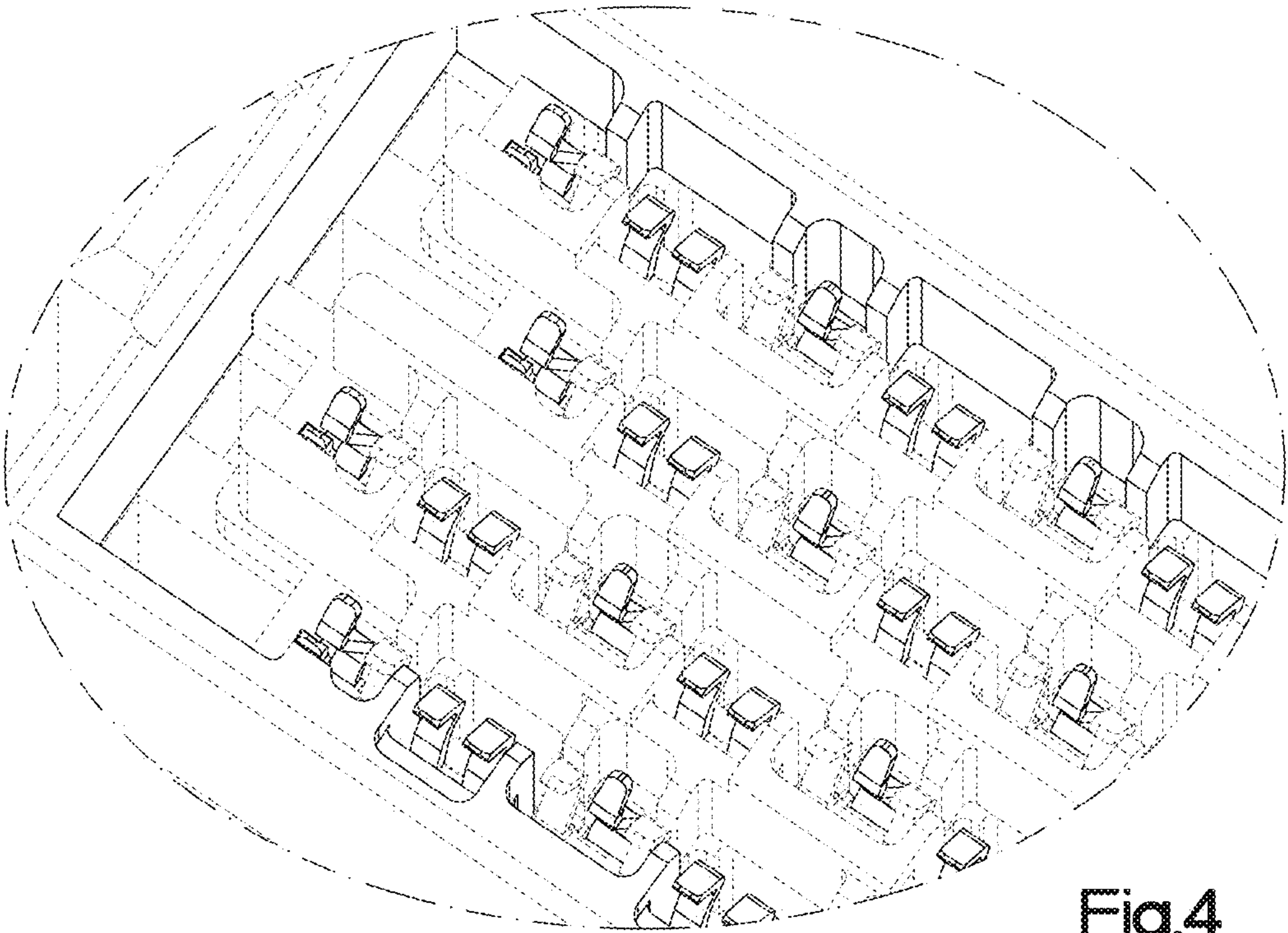


Fig.4

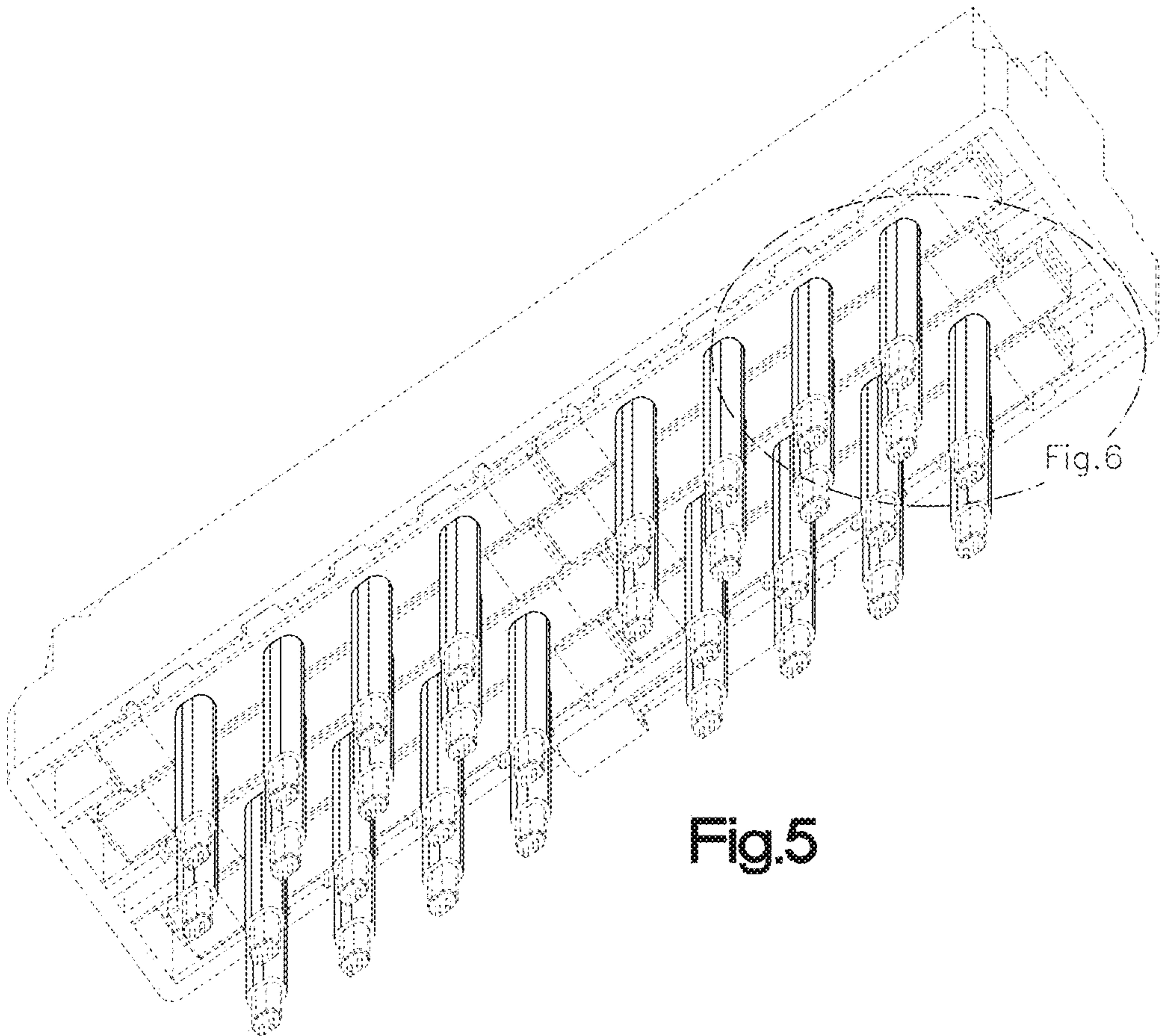


Fig. 6

Fig. 5

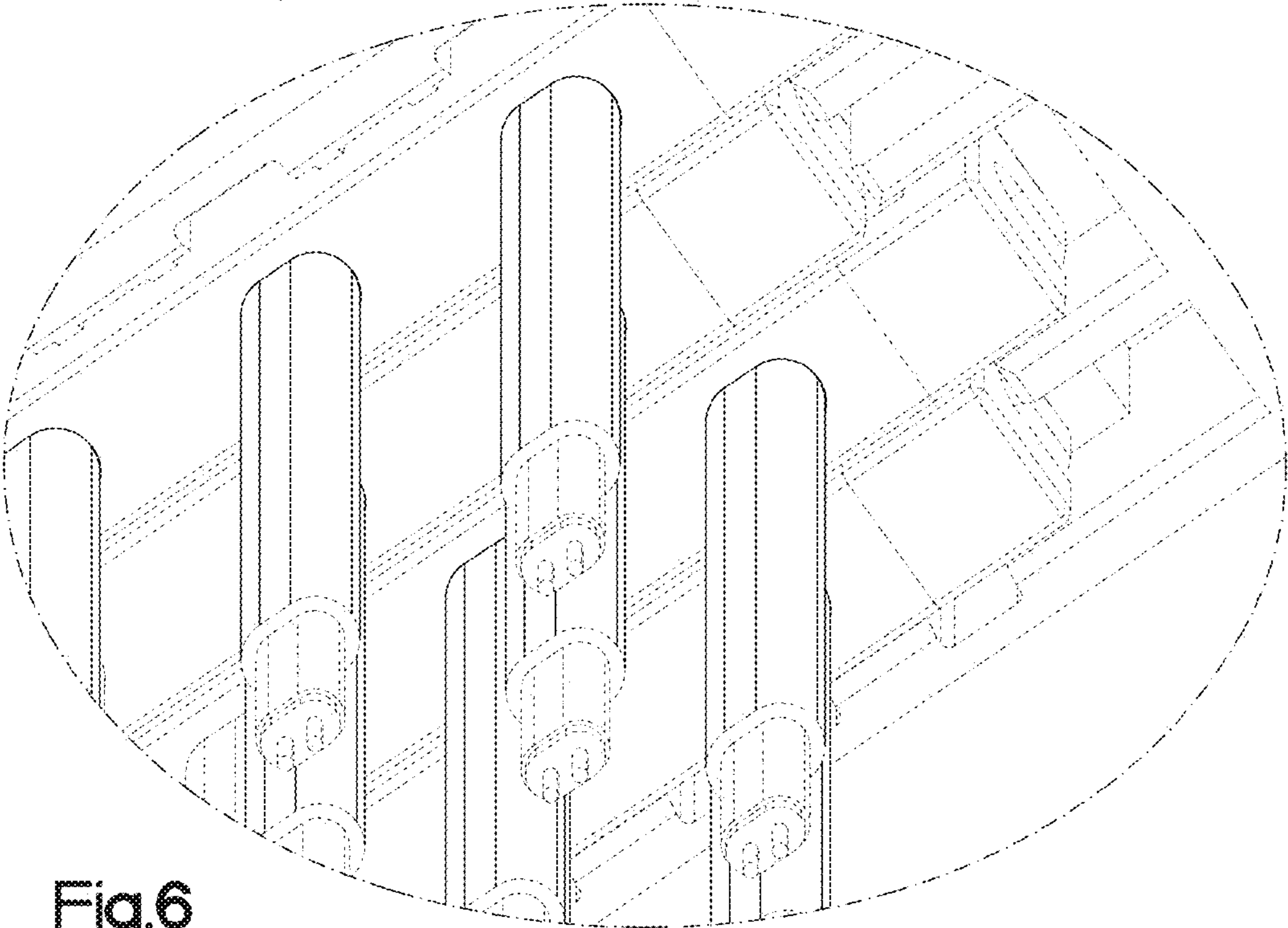


Fig. 6

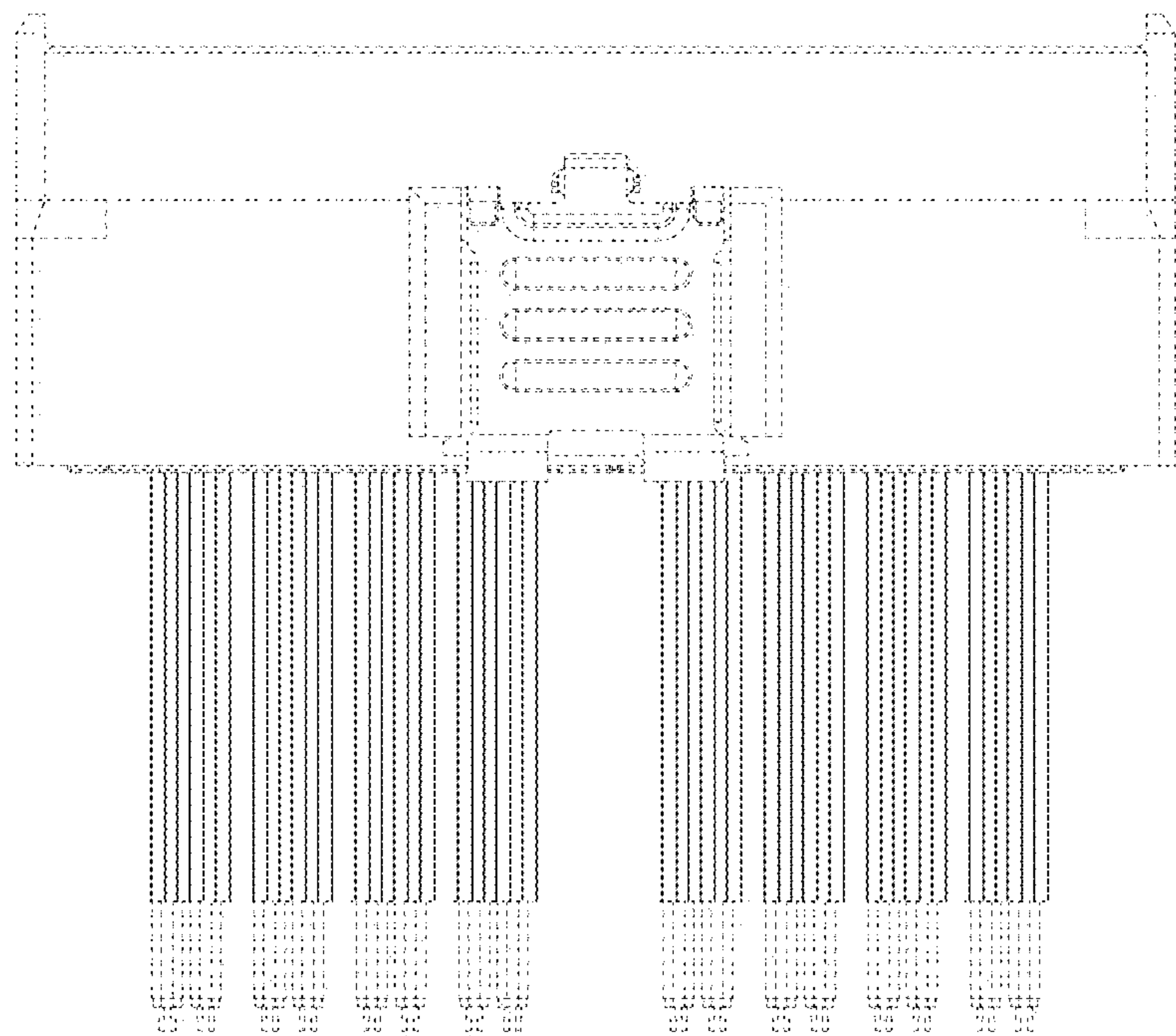


Fig.7

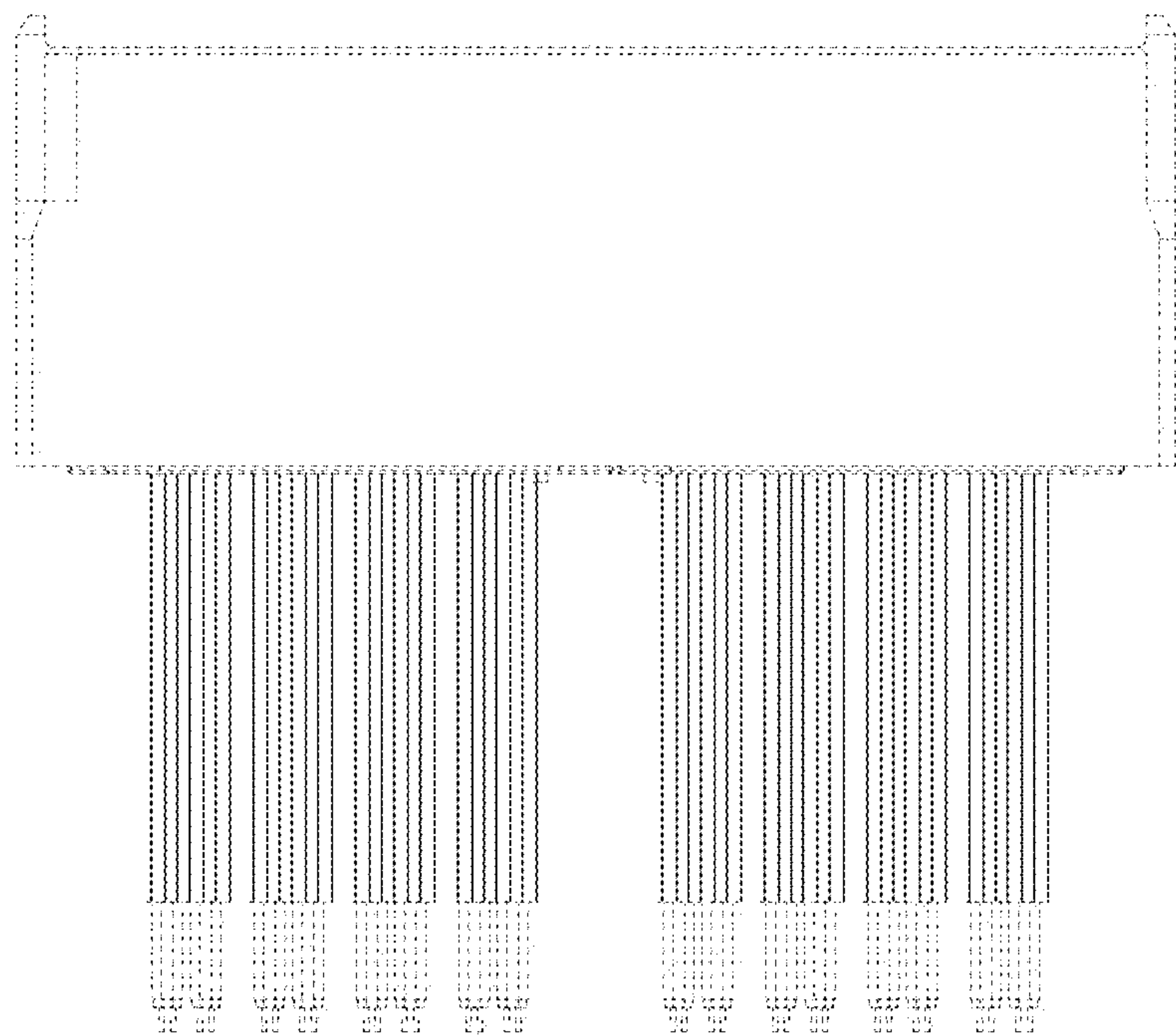


Fig.8

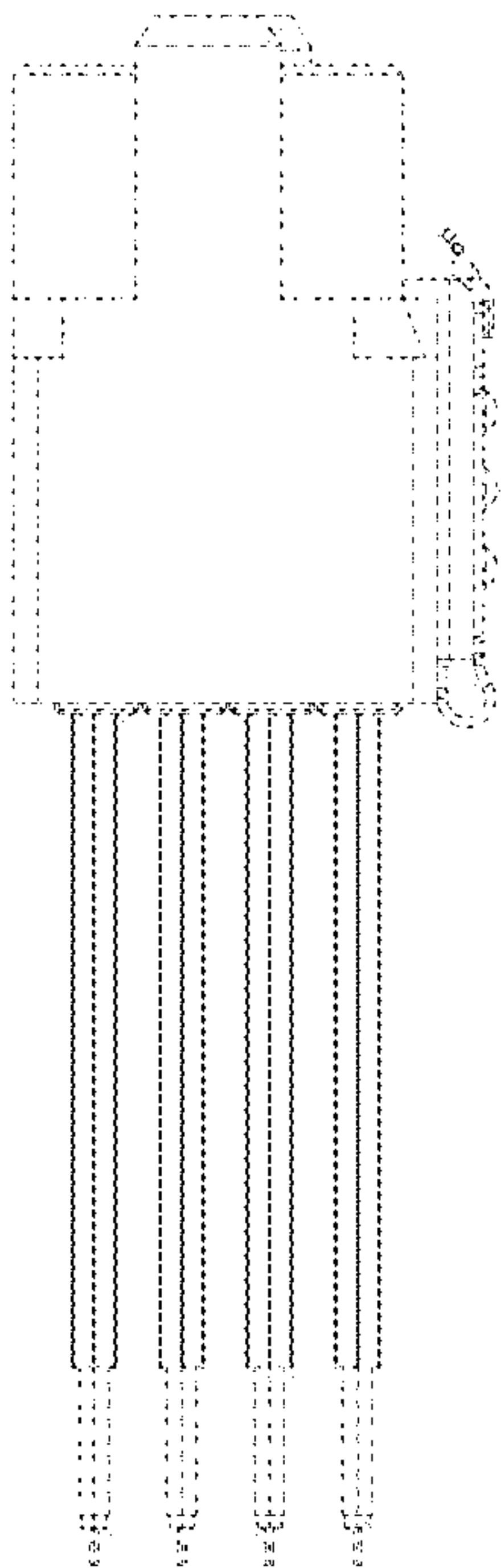


Fig.9

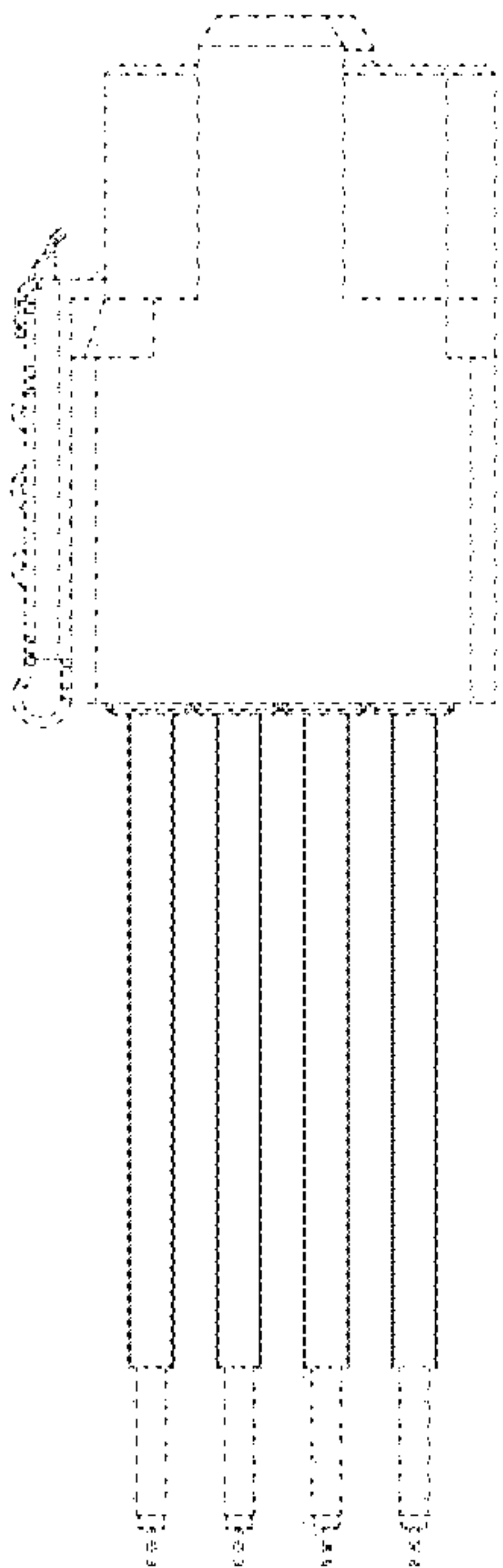


Fig.10

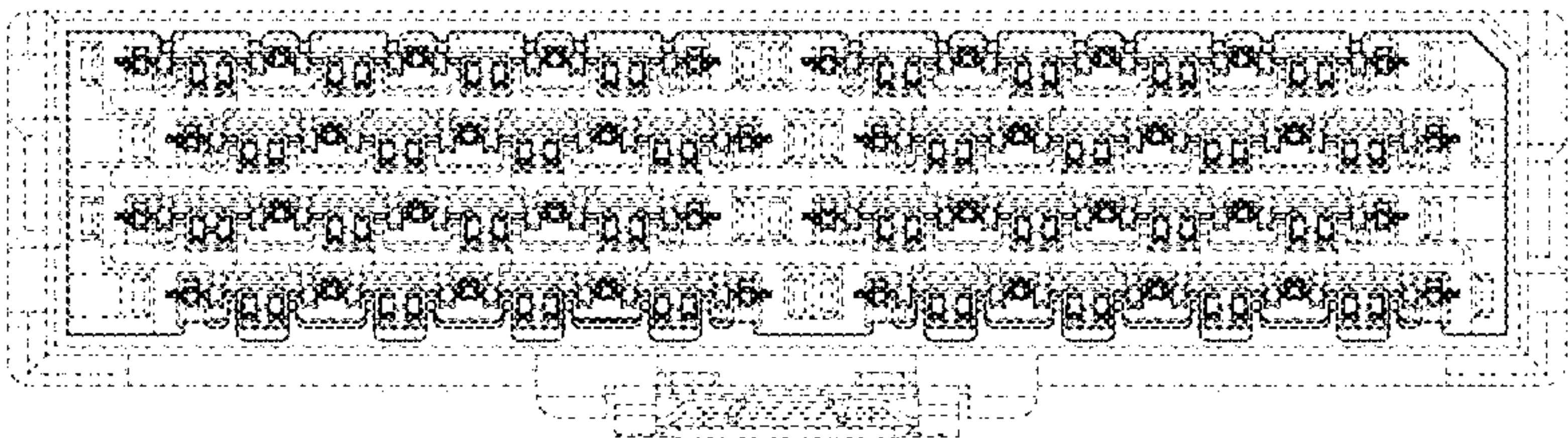


Fig.11

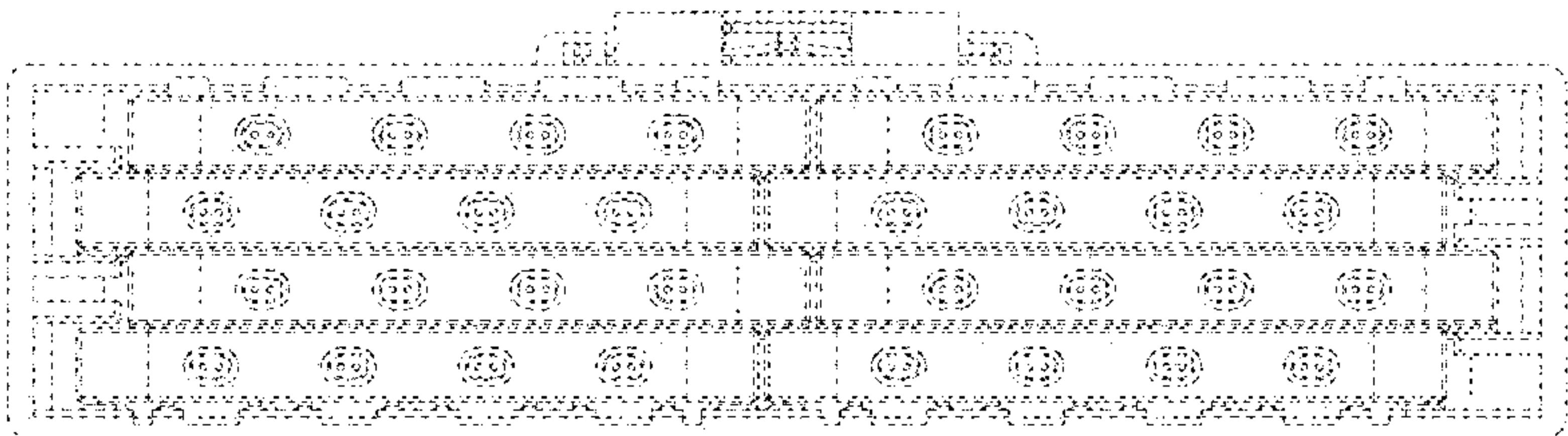


Fig.12